

Electronic Patent Application Fee Transmittal

Application Number:	10672778			
Filing Date:	26-Sep-2003			
Title of Invention:	Atomic layer deposition (ALD) method with enhanced deposition rate			
First Named Inventor:	Chih-Ta Wu			
Filer:	Daniel R. McClure			
Attorney Docket Number:	252016-3000			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1202	1	50	50
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				50